

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



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PLED

## LMV321M5X(MS)

Product specification

## DESCRIPTION

The LMV321M5X(MS) is single low voltage (2.7V to 5.5V) operational amplifier which has rail-to-rail output swing capability. The input common-mode voltage range includes ground. The chip exhibits excellent speed-power ratio, achieving 1MHz of bandwidth and 1V/ $\mu$ s of slew rate with low supply current.

The LMV321M5X(MS) S is built with BiCMOS process. It has bipolar input and output stages for improved noise performance, low input offset and higher output current drive.

The LMV321M5X(MS) is available in the package of SOT-23-5.

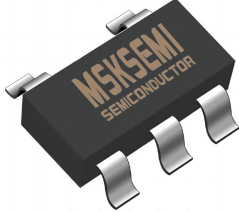
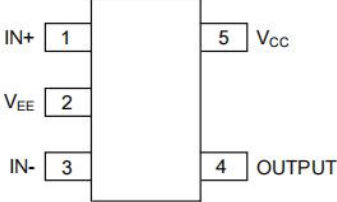

## FEATURES (For $V_{CC}=5V$ and $V_{EE}=0V$ , Typical unless Otherwise Noted)

- Guaranteed 2.7V to 5.5V Performance
- No Crossover Distortion
- Gain-Bandwidth Product 1 MHz
- Industrial Temperature Range:  $-40^{\circ}C$  to  $+85^{\circ}C$
- Low Supply Current: 130 $\mu$ A
- Rail-to-Rail Output Swing under 10k $\Omega$  Load:
- $V_{OH}$  up to  $V_{CC}-10mV$
- $V_{OL}$  near to  $V_{EE}+65mV$
- $V_{CM}$  : -0.1V to  $V_{CC}-0.8V$

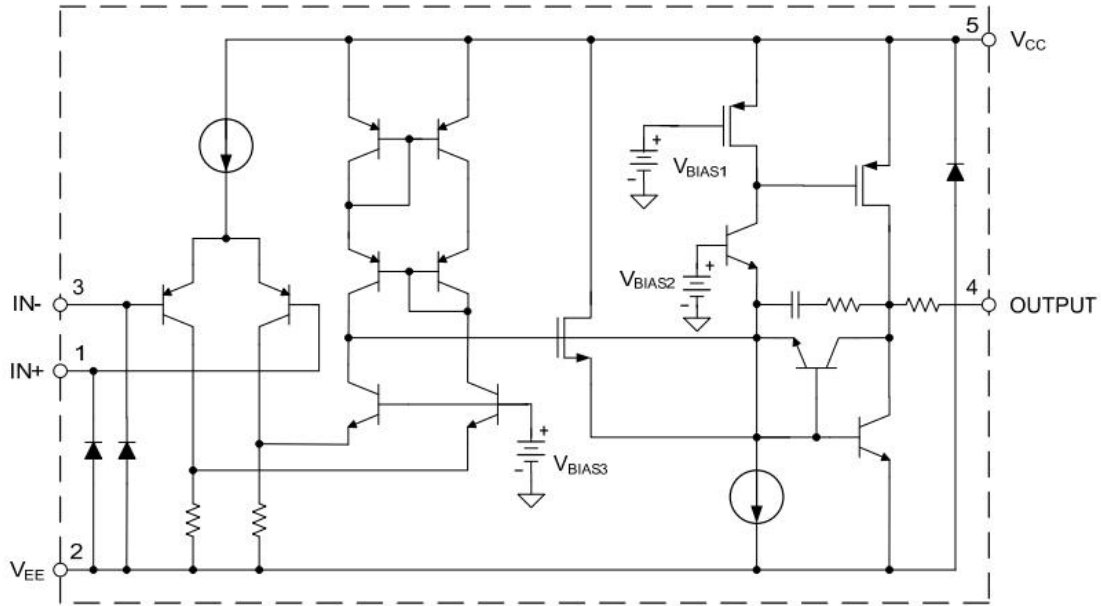
## Applications

- Active Filters
- Low Power, Low Voltage Applications
- General Purpose Portable Devices
- Cellular Phone, Cordless Phone
- Battery-Powered Systems

## Reference News

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		
SOT-23-5	IDBV/IDCK Package	SOT-23-5

## Functional Block Diagram



## Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
VCC	Power Supply Voltage	6	V
TJ	Operation Junction Temperature	150	°C
TSTG	Storage Temperature Range	-65 to 150	°C
TLEAD	Lead Temperature (Soldering, 10 Seconds)	260	°C
	ESD (Machine Model)	200	V
	ESD (Human Body Model)	2000	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

## Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
VCC	Supply Voltage	2.7	5.5	V
TA	Ambient Operating Temperature Range	-40	85	°C

## Electrical Characteristics

**LMV321-2.7V Electrical Characteristic**(Asll limits are guaranteed for TA=25°C, VCC=2.7V, VEE=0V, VCM=1.0V, VO=VCC/2 and RL>1MΩ , limits in bold types are guaranteed for TA=-40°C to 85°C, unless otherwise specified. Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VIO	Input Offset Voltage			1.7	7 <b>9</b>	mV
IB	Input Bias Current			11	250 <b>500</b>	nA
IIO	Input Offset Current			5	50 <b>150</b>	nA
VCM	Input Common Mode Voltage Range	for CMRR≥50dB	-0.1		1.9	V
ICC	Supply Current	VO=VCC/2, AVCL=1, no load		80	170 <b>270</b>	μA
CMRR	Common Mode Rejection Ratio	0≤VCM≤ 1.7V	50	65		dB
PSRR	Power Supply Rejection Ratio	2.7V≤VCC≤5V, VO=1V	50	60		dB
ISOURCE	Output Short Circuit Current	VO=0V	5	20		mA
ISINK		VO=2.7V	10	30		mA
VOH	Output Voltage Swing	RL=10kΩ to 1.35V	2.60	2.69		V
VOL				60	180	
GBWP	Gain Bandwidth Product	CL=200pF		1		MHz
OM	Phase Margin			60		Deg
GM	Gain Margin			10		dB

Note 2: Limits over the full temperature are guaranteed by design, but not tested in production.

## Electrical Characteristics (Cont.)

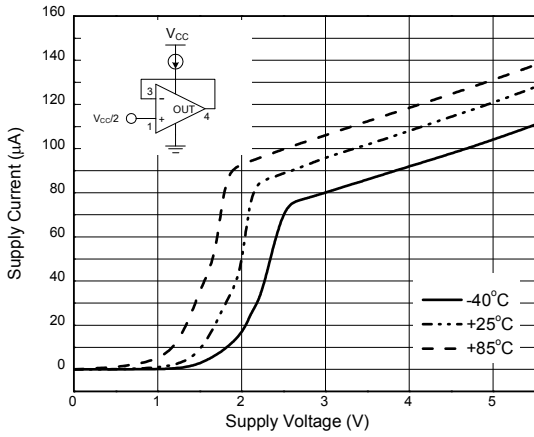
**LMV321-5V Electrical Characteristics** (All limits are guaranteed for TA=25°C, VCC=5V, VEE=0V, VCM=2.0V, VO=VCC/2 and RL>1MΩ, limits in bold types are guaranteed for TA=-40°C to 85°C, unless otherwise specified. Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VIO	Input Offset Voltage			1.7	7	mV
					<b>9</b>	
IB	Input Bias Current			11	250	nA
					<b>500</b>	
IIO	Input Offset Current			5	50	nA
					<b>150</b>	
VCM	Input Common Mode Voltage Range	for CMRR≥50dB	-0.1		4.2	V
ICC	Supply Current	VO=VCC/2, AVCL=1, no load		130	250	μA
					<b>350</b>	
GV	Large Signal Voltage Gain	RL=2kΩ	84	100		dB
			<b>80</b>			
CMRR	Common Mode Rejection Ratio	0≤VCM≤4V	50	65		dB
PSRR	Power Supply Rejection Ratio	2.7V≤VCC≤5V, VO=1V, VCM=1V	50	60		dB
ISOURCE	Output Short Circuit Current	VO=0V	5	60		mA
ISINK		VO=5V	10	160		mA
VOH	Output Voltage Swing	RL=2kΩ to 2.5V	4.7	4.96		V
			<b>4.6</b>			
		RL=10kΩ to 2.5V	4.9	4.99		
			<b>4.8</b>			
VOL	Output Voltage Swing	RL=2kΩ to 2.5V		120	300	mV
					<b>400</b>	
		RL=10kΩ to 2.5V		65	180	
					<b>280</b>	
SR	Slew Rate			1		V/μS
GBWP	Gain Bandwidth Product	CL=200pF		1		MHz
OM	Phase Margin			60		Deg
GM	Gain Margin			10		dB

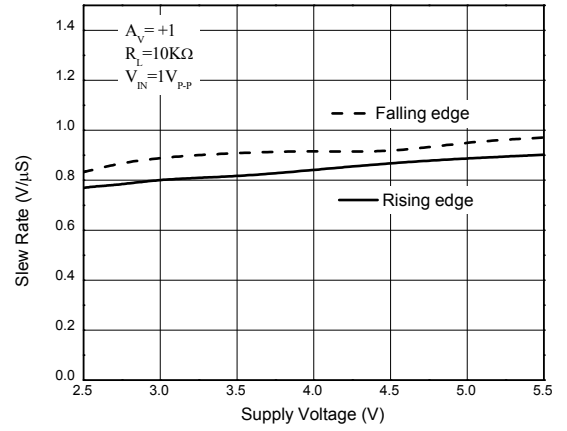
Note 2: Limits over the full temperature are guaranteed by design, but not tested in production.

**Performance Characteristics**

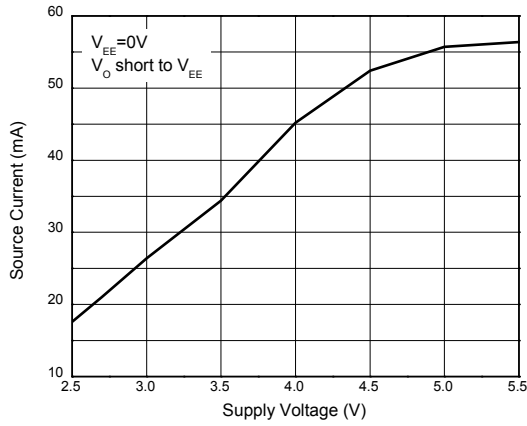
**Supply Current vs. Supply Voltage**



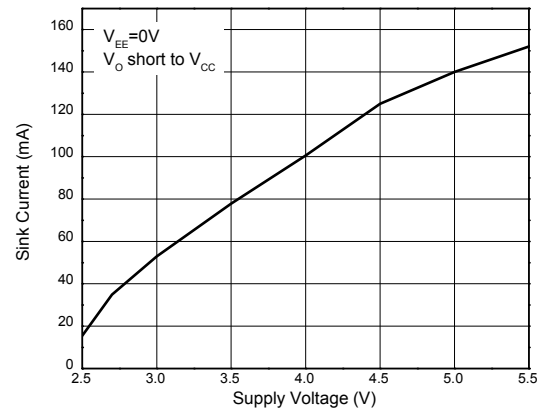
**Slew Rate vs. Supply Voltage**



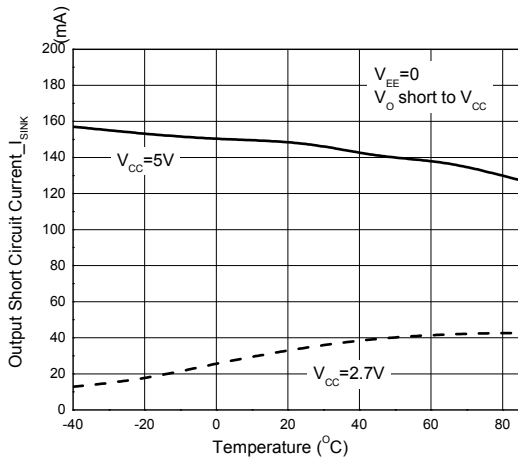
**Output Source Current vs. Supply Voltage**



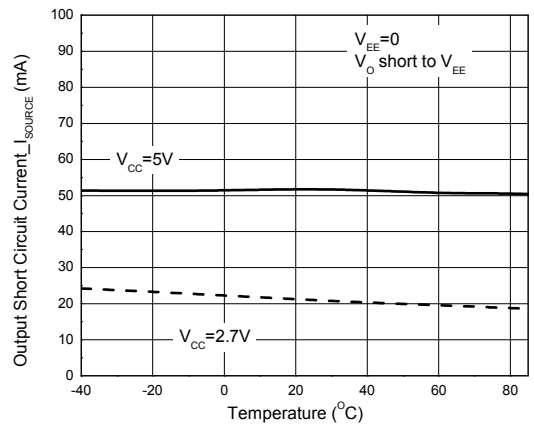
**Output Sink Current vs. Supply Voltage**



**Short Circuit Current  $I_{SINK}$  vs. Temperature**

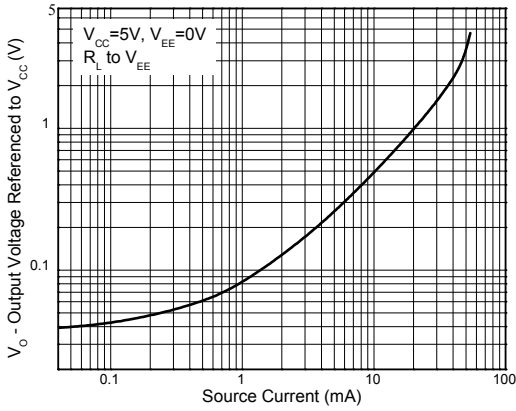


**Short Circuit Current  $I_{SOURCE}$  vs. Temperature**

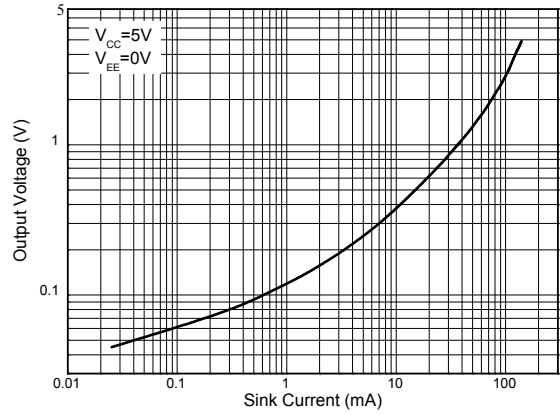


**Performance Characteristics (Cont.)**

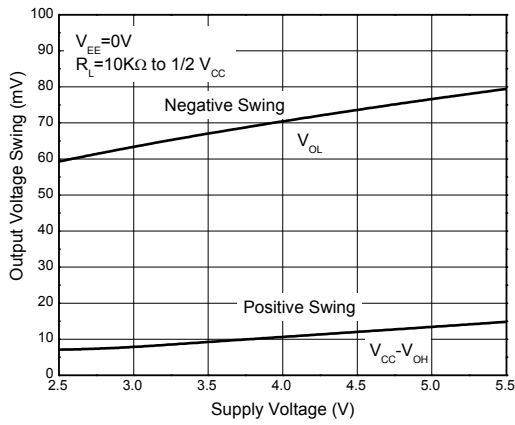
**Output Voltage vs. Source Current**



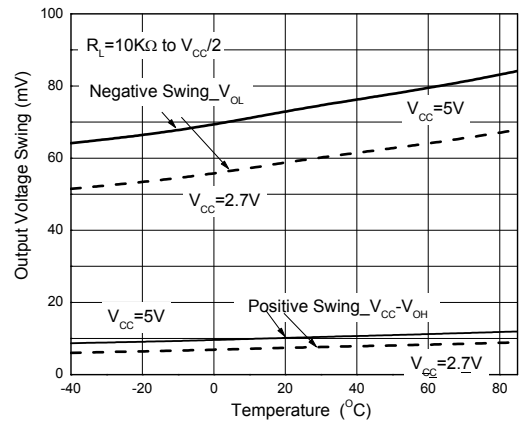
**Output Voltage vs. Sink Current**



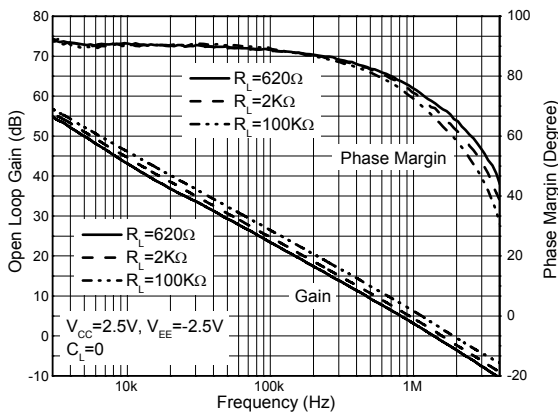
**Output Voltage Swing vs. Supply Voltage**



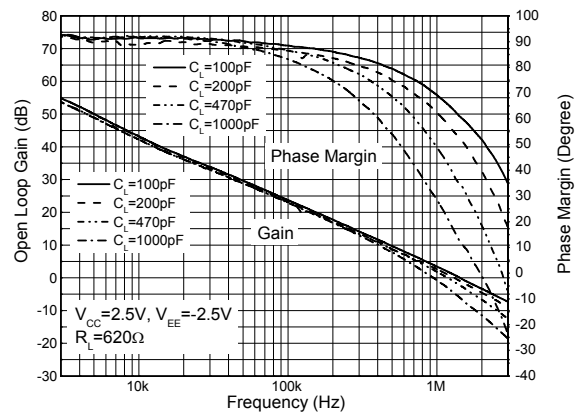
**Output Voltage Swing vs. Temperature**



**Gain and Phase vs. Frequency and Resistive Load**

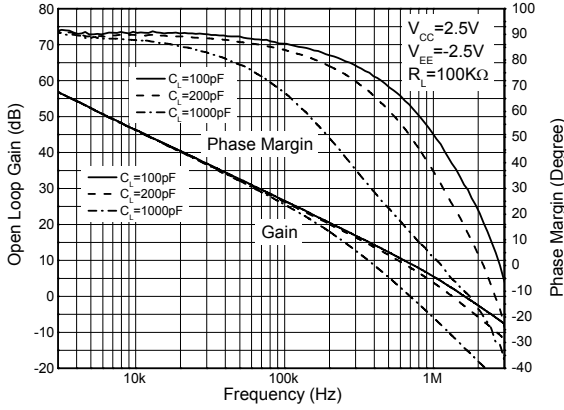


**Gain and Phase vs. Frequency and Capacitive Load**

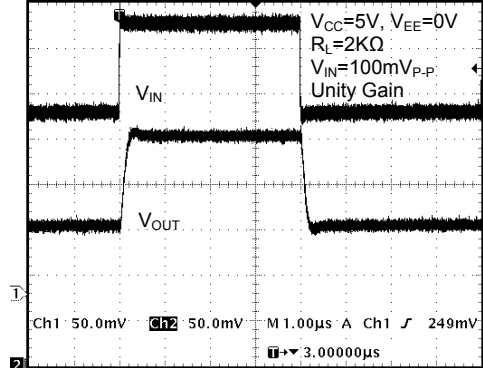


**Performance Characteristics (Cont.)**

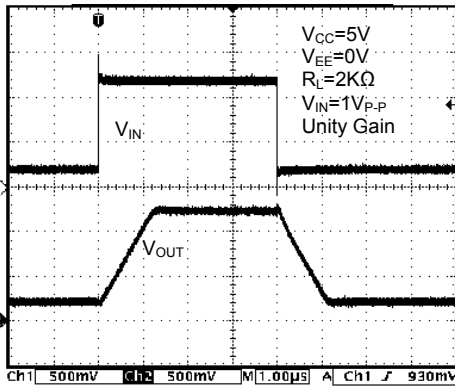
**Gain and Phase vs. Frequency and Capacitive Load**



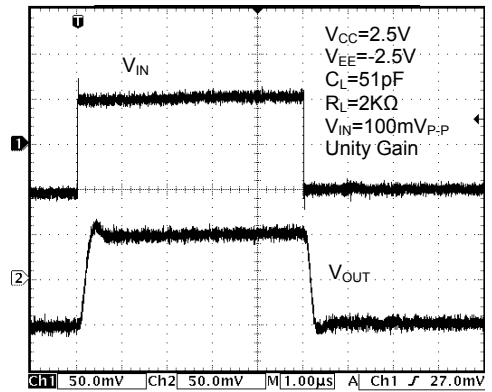
**Non-Inverting Input Small Signal Pulse Response**



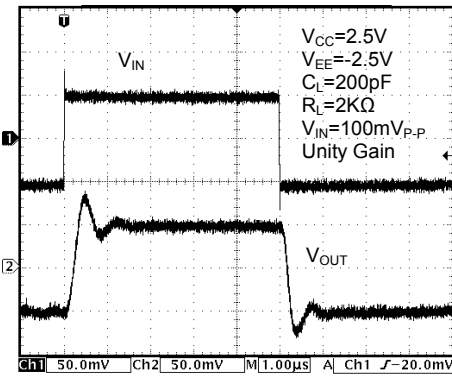
**Non-Inverting Input Large Signal Pulse Response**



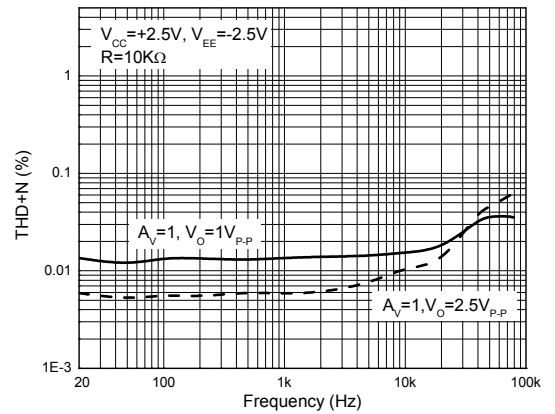
**Output with Excessive Capacitive Load**



**Output with Excessive Capacitive Load**

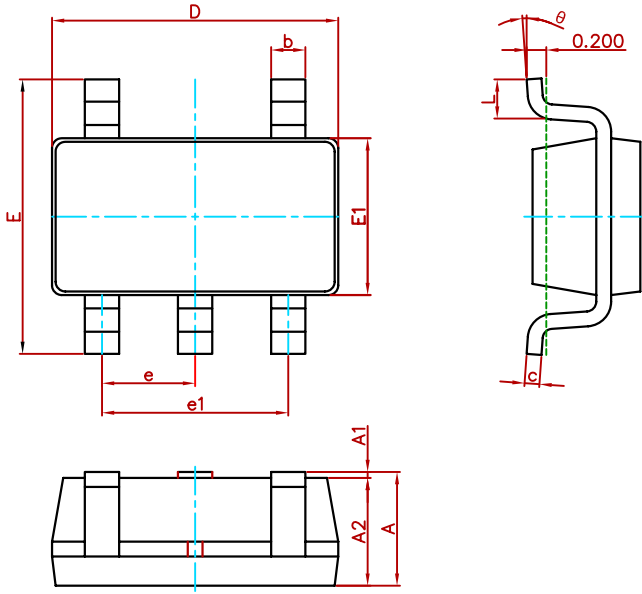


**THD+N vs. Frequency**



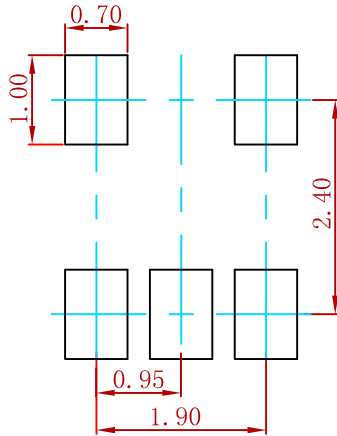


**SOT-23-5L Package Outline Dimensions**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	2.650	2.950	0.104	0.116
E1	1.500	1.700	0.059	0.067
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

**SOT-23-5L Suggested Pad Layout**



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance: ± 0.05mm.  
 3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
LMV321M5X (MS)	SOT-23-5	3000pcs

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